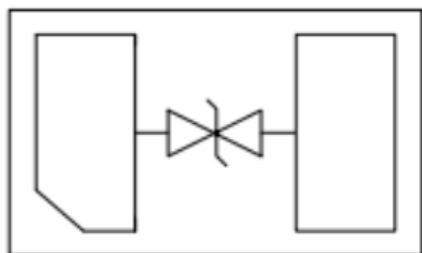




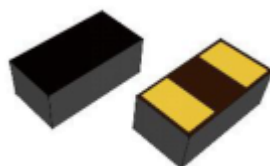
Description

The JLE12BMD2 -2 help protect sensitive electronic equipment against electrostatic discharge (ESD). They supplement the on-chip protection of integrated circuitry and are best suited for low-voltage, high-speed applications where low capacitance is important. Data ports utilizing such high-speed protocols as USB 2.0, IEEE1394, HDMI and DVI can benefit from this new technology.

Circuit Diagram



Package Outline



Features

- * Ultra-Low capacitance: 0.05pF (typ.)
- * Low leakage current: (<10nA)
- * Fast response time: (<1ns)
- * Bi-directional, single line protection
- * 2-pin leadless package
- * Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
 - Air discharge: ±15kV
 - Contact discharge: ±8kV
- * RoHS Compliant
- * Package: DFN1006-2

Applications

- * HDTV Hardware
- * Computer Peripherals
- * Laptop/Desktop Computers
- * Digital Cameras
- * External Storage
- * Network Hardware
- * Set-Top Boxes
- * USB 3.0/3.1
- * HDMI 1.3/1.4/2.0

Ordering Information

Part Number	Packaging	Reel Size
JLE12BMD2 -2	10000/Tape & Reel	7 inch



JLE12BMD2-2

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

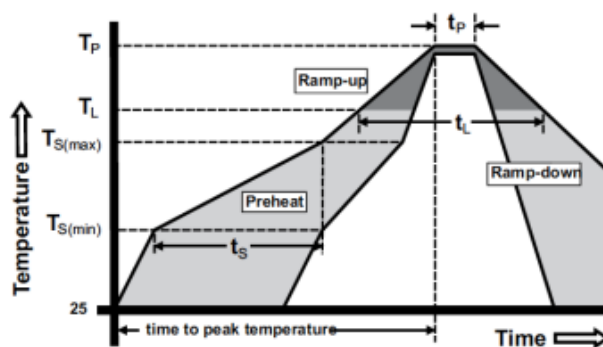
Parameter	Symbol	Value	Unit
ESD per IEC 61000-4-2 (Air)	VESD	± 15	kV
ESD per IEC 61000-4-2 (Contact)		± 8	
Operating Temperature Range	TJ	-40 to +120	$^\circ\text{C}$
Storage Temperature Range	Tstg	-40 to + 85	$^\circ\text{C}$

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Continuous Operating Voltage	V_{DC}				12	V
Trigger Voltage	V_T	IEC61000-4-2 8KV Contact		45		V
Clamping Voltage	V_C	IEC61000-4-2 8KV Contact		40		V
Leakage Current	I_L	DC 12V shall be applied on component			10	nA
Junction Capacitance	C_J	Measured at 10MHz		0.05		pF

Soldering Parameters

Reflow Condition	Pb - Free assembly	
Pre Heat	- Temperature Min ($T_{s(min)}$)	150 $^\circ\text{C}$
	- Temperature Max ($T_{s(max)}$)	200 $^\circ\text{C}$
	- Time (min to max) (t_b)	60 - 180 seconds
Average ramp up rate (Liquidus Temp (T_L) to peak)	3 $^\circ\text{C}/\text{second}$ max	
$T_{s(max)}$ to T_L - Ramp-up Rate	3 $^\circ\text{C}/\text{second}$ max	
Reflow	- Temperature (T_L) (Liquidus)	217 $^\circ\text{C}$
	- Temperature (t_L)	60 - 150 seconds
Peak Temperature (T_p)	260 $^\circ\text{C}$	
Time within 5 $^\circ\text{C}$ of actual peak Temperature (t_p)	10 - 30 seconds	
Ramp-down Rate	6 $^\circ\text{C}/\text{second}$ max	
Time 25 $^\circ\text{C}$ to peak Temperature (T_p)	8 minutes max	





JLE12BMD2-2

Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise Specified)

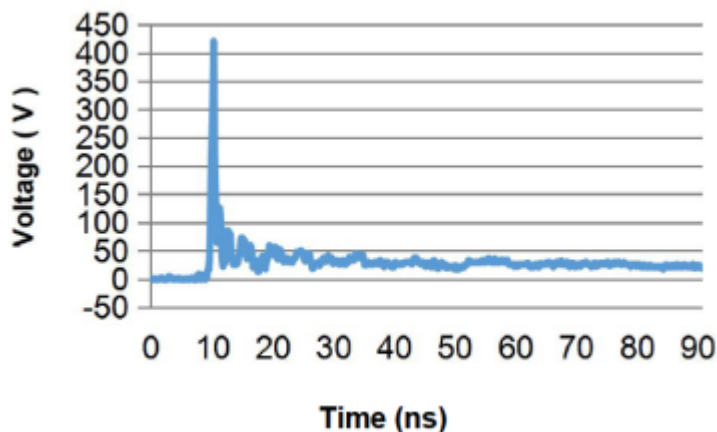


Figure 1. Typical ESD Response

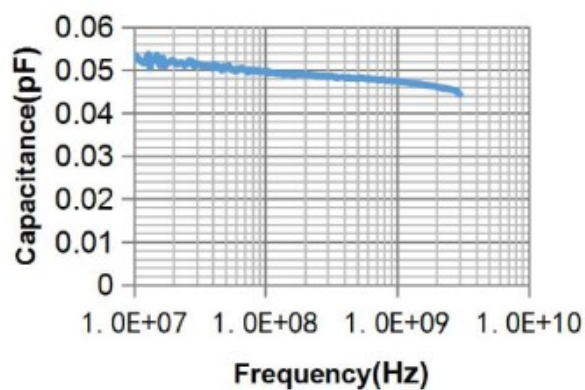


Figure 2. Typical Capacitance vs. Frequency

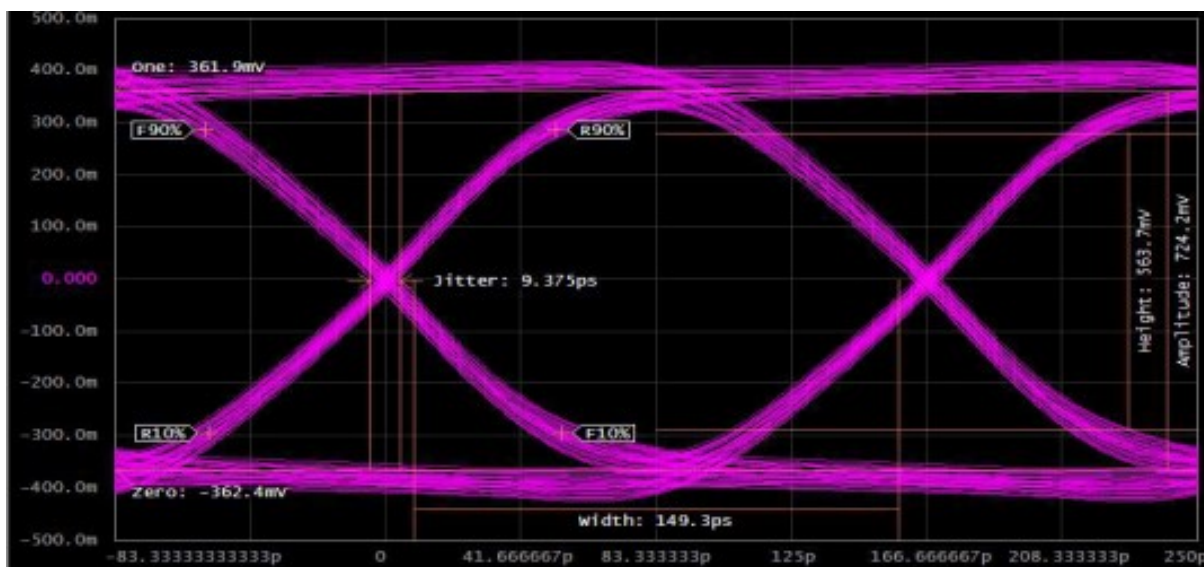
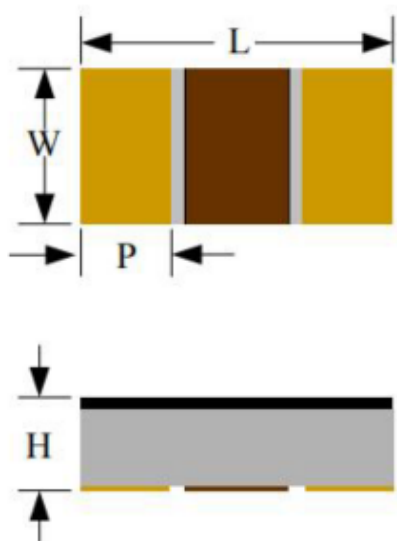


Figure 3. HDMI 2.0 Mask at 6.0 Gbps



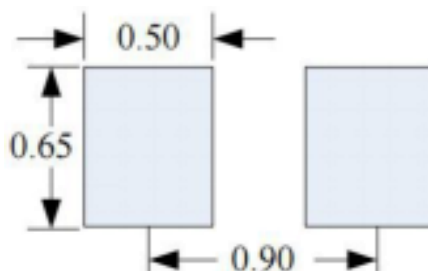
JLE12BMD2-2

DFN1006-2 Package Outline Drawing



<i>Dim</i>	<i>Millimeters</i>	
	<i>Min</i>	<i>Max</i>
<i>L</i>	0.90	1.10
<i>W</i>	0.42	0.62
<i>P</i>	0.15	0.35
<i>H</i>	0.25	0.45

Suggested Land Pattern



*Sizes in mm

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